DISCRETE SEMICONDUCTORS

DATA SHEET



BGU2003 SiGe MMIC amplifier

Preliminary specification

2002 May 17







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FEATURES

- Low current
- Very high power gain
- · Low noise figure
- Integrated temperature compensated biasing
- · Control pin for adjustment bias current
- Supply and RF output pin combined.

APPLICATIONS

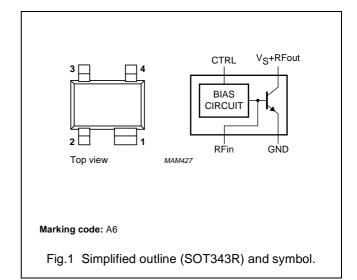
- RF front end
- Wideband applications, e.g. analog and digital cellular telephones, cordless telephones (PHS, DECT, etc.)
- · Low noise amplifiers
- Satellite television tuners (SATV)
- · High frequency oscillators.

DESCRIPTION

Silicon MMIC amplifier consisting of an NPN double polysilicon transistor with integrated biasing for low voltage applications in a plastic, 4-pin SOT343R package.

PINNING

PIN	DESCRIPTION				
1	GND				
2	RF in				
3	CTRL (bias current control)				
4	V _S + RF out				



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _S	DC supply voltage	RF input AC coupled	_	4.5	V
I _S	DC supply current	V _{VS-OUT} = 2.5 V; I _{CTRL} = 1 mA; RF input AC coupled	10	_	mA
MSG	maximum stable gain	$V_{VS-OUT} = 2.5 \text{ V}; f = 1800 \text{ MHz};$ $T_{amb} = 25 ^{\circ}\text{C}$	18	_	dB
NF	noise figure	V_{VS-OUT} = 2.5 V; f = 1800 MHz; Γ_S = Γ_{opt}	1.1	_	dB

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Vs	supply voltage	RF input AC coupled	_	4.5	V
V _{CTRL}	voltage on control pin		_	2	V
I _S	supply current (DC)	forced by DC voltage on RF input or I _{CTRL}	_	30	mA
I _{CTRL}	control current		_	3	mA
P _{tot}	total power dissipation	T _s ≤ 100 °C	_	135	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	operating junction temperature		_	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	350	K/W

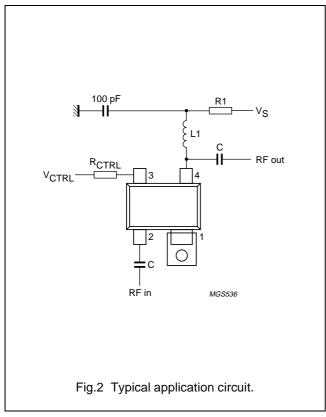
CHARACTERISTICS

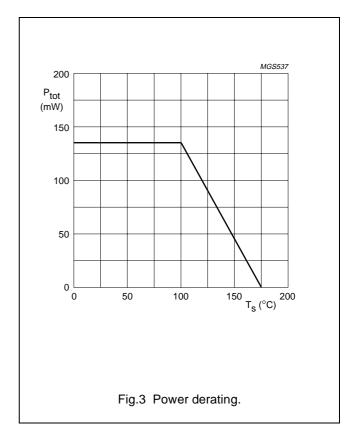
RF input AC coupled; T_j = 25 °C; unless otherwise specified.

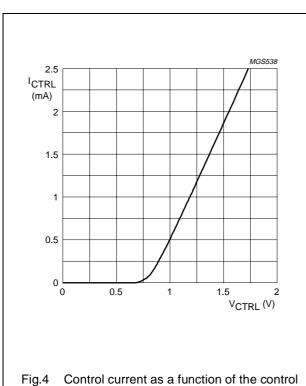
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _S	supply current	$V_{VS-OUT} = 2.5 \text{ V}; I_{CTRL} = 0.4 \text{ mA}$	2.5	4.5	6.5	mA
		$V_{VS-OUT} = 2.5 \text{ V}; I_{CTRL} = 1.0 \text{ mA}$	6	10	15	mA
MSG	maximum stable gain	$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 10 \text{ mA};$ f = 900 MHz	_	23	_	dB
		$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 10 \text{ mA};$ f = 1800 MHz	_	18	_	dB
S ₂₁ ²	insertion power gain	$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 10 \text{ mA};$ f = 900 MHz	18	19	_	dB
		$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 10 \text{ mA};$ f = 1800 MHz	13	14	_	dB
s ₁₂	isolation	$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 0;$ f = 900 MHz	_	26	_	dB
		$V_{VS-OUT} = 2.5 \text{ V}; I_{VS-OUT} = 0;$ f = 1800 MHz	_	20	_	dB
NF	noise figure	V_{VS-OUT} = 2.5 V; I_{VS-OUT} = 10 mA; f = 900 MHz; Γ_S = Γ_{opt}	_	1.0	2	dB
		V_{VS-OUT} = 2.5 V; I_{VS-OUT} = 10 mA; f = 1800 MHz; Γ_S = Γ_{opt}	_	1.1	2	dB
IP3 _(out)	output intercept point; $Z_S = Z_L 50 \Omega$	$V_{VS-OUT} = 2.3 \text{ V; } I_{VS-OUT} = 10 \text{ mA;}$ f = 900 MHz	_	19	_	dBm
		$V_{VS-OUT} = 2.3 \text{ V; } I_{VS-OUT} = 10 \text{ mA;}$ f = 1800 MHz	_	21	_	dBm

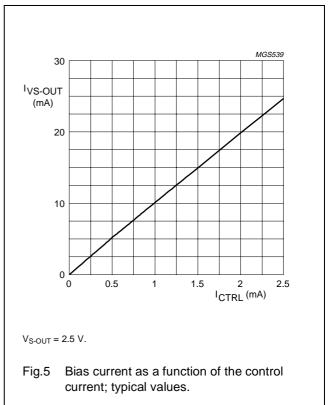
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voltage on pin 3; typical values.

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Scattering parameters: V_S = 2.5 V; I_S = 10 mA; T_{amb} = 25 °C

	S ₁₁		S ₂₁		S ₁₂		S ₂₂		
f (MHz)	MAGNITUDE (ratio)	ANGLE (deg)							
100	0.837	-10.6	19.216	163.9	0.007	77.3	0.976	-7.1	
200	0.783	-19.9	17.589	151.7	0.012	77.2	0.920	-13.2	
300	0.713	-28.4	16.321	142.4	0.018	76.7	0.861	-17.1	
400	0.645	-36.0	15.046	134.5	0.022	72.9	0.805	-19.8	
500	0.581	-42.0	13.701	127.7	0.027	75.2	0.759	-21.9	
600	0.519	-47.1	12.709	121.6	0.031	74.8	0.718	-22.8	
700	0.474	-50.8	11.602	116.8	0.034	75.0	0.689	-23.4	
800	0.433	-53.3	10.631	112.6	0.038	75.3	0.664	-24.1	
900	0.397	-55.2	9.791	108.8	0.042	76.3	0.644	-24.4	
1000	0.369	-56.9	8.951	106.0	0.046	76.1	0.627	-25.2	
1100	0.342	-58.4	8.314	103.6	0.050	77.3	0.610	-25.6	
1200	0.320	-60.2	7.730	101.1	0.055	77.6	0.599	-26.4	
1300	0.301	-62.1	7.275	99.4	0.058	78.4	0.591	-27.2	
1400	0.286	-64.4	6.912	97.1	0.063	78.1	0.583	-28.0	
1500	0.273	-66.7	6.493	94.8	0.066	78.2	0.578	-28.6	
1600	0.262	-68.5	6.078	93.5	0.071	78.9	0.572	-29.0	
1700	0.252	-7.08	5.783	91.8	0.074	78.9	0.564	-29.6	
1800	0.241	-73.7	5.475	90.9	0.078	79.8	0.553	-30.0	
1900	0.229	-77.0	5.289	89.9	0.083	79.7	0.543	-30.7	
2000	0.221	-81.1	5.094	88.4	0.088	79.5	0.530	-31.9	
2100	0.216	-85.5	4.911	87.2	0.092	79.4	0.518	-33.6	
2200	0.215	-88.9	4.779	85.6	0.098	79.6	0.512	-35.6	
2300	0.229	-91.6	4.588	84.3	0.104	78.7	0.515	-38.2	
2400	0.237	-97.0	4.446	83.8	0.107	78.6	0.515	-40.7	
2500	0.240	-99.3	4.325	82.3	0.111	79.1	0.523	-42.3	
2600	0.243	-101.1	4.145	81.9	0.115	80.1	0.532	-43.0	
2700	0.243	-102.9	4.105	81.6	0.121	80.4	0.537	-43.3	
2800	0.238	-104.9	4.038	80.2	0.124	80.4	0.538	-43.0	
2900	0.233	-106.8	3.924	78.5	0.129	80.3	0.532	-43.2	
3000	0.224	-109.0	3.795	76.7	0.132	80.0	0.519	-43.1	

Noise parameters: V_S = 2.5 V; I_S = 10 mA; T_{amb} = 25 $^{\circ}\text{C}$

f /MU=\	NE (dD)	gamma o	D /500	
f (MHz)	NF _{min} (dB)	MAGNITUDE (ratio)	ANGLE (deg)	R _n / 50 Ω
900	1.0	0.19	14	0.16
1800	1.1	0.08	60	0.14
2500	1.3	0.07	90	0.14

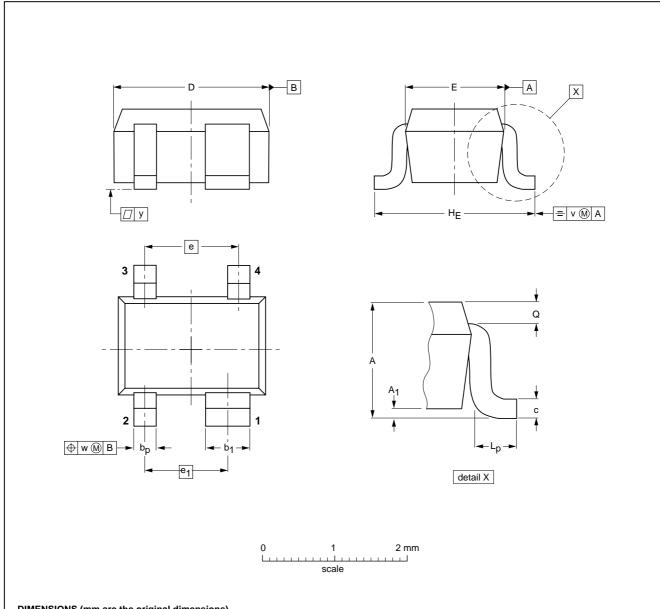
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PACKAGE OUTLINE

Plastic surface mounted package; reverse pinning; 4 leads

SOT343R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	b ₁	С	D	E	е	e ₁	HE	Lp	Q	v	w	у
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE	REFERENCES EUROPEAN					ICCUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT343R						97-05-21	

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